

	Type	L #	Hits	Search Text	DBs
1	BRS	L1	1991	257/787.ccls.	US-PGPUB; USPAT; USOCR
2	BRS	L2	1315	257/780.ccls.	US-PGPUB; USPAT; USOCR
3	BRS	L3	1720	257/784.ccls.	US-PGPUB; USPAT; USOCR
4	BRS	L4	1790	257/787.ccls.	EPO; JPO; DERWENT; IBM_TDB
5	BRS	L5	453	257/784.ccls.	EPO; JPO; DERWENT; IBM_TDB
6	BRS	L6	98	257/780.ccls.	EPO; JPO; DERWENT; IBM_TDB
7	BRS	L7	411	257/E23.119.ccls.	EPO; JPO
8	BRS	L8	0	L7 and (resin or adhesive or encap)	US-PGPUB; USPAT
9	BRS	L9	0	L7 and resin	US-PGPUB; USPAT
10	BRS	L10	337	L7 and (resin or adhesive or encap)	EPO; JPO
11	BRS	L11	0	L10 and (oblique or angle) and (surface or area)	US-PGPUB; USPAT

	Type	L #	Hits	Search Text	DBs
12	BRS	L12	10	((chip or die) and (resin or seal\$3 or encapsula\$2 or protective or molding) and thickness and (substrate or board or interposer) and wiring and angle and (boundary or periphery)).clm.	US-PGPUB